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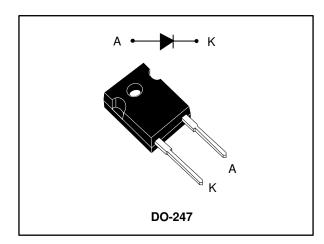


STBR6012-Y



Automotive high voltage rectifier for bridge applications

Datasheet - production data



Features

- AEC-Q101 qualified
- Ultra-low conduction losses
- Ultra-low reverse losses
- High junction temperature capability
- V_{RRM} guaranteed from -40 to +175 °C
- ECOPACK®2 compliant component
- PPAP capable

Description

The high quality design of this diode results in a device with consistently reproducible characteristics and intrinsic ruggedness. These characteristics make it ideal for heavy duty applications that demand long term reliability like automotive applications.

Thanks to its ultra-low conduction losses, this diode is especially suitable for use as input bridge diode in battery chargers.

Table 1: Device summary

Symbol	Value
I _{F(AV)}	60 A
V_{RRM}	1200 V
V _F (typ.)	0.95 V
T _j	-40 to +175 °C

Characteristics STBR6012-Y

1 Characteristics

Table 2: Absolute ratings (limiting values at 25 °C, unless otherwise specified)

Symbol	Param	Value	Unit	
V _{RSM}	Non-repetitive surge reverse voltage		1500	V
V_{RRM}	Repetitive peak reverse voltage	T _j = -40 °C to +175 °C	1200	V
I _{F(RMS)}	Forward rms current	90	Α	
I _{F(AV)}	Average forward current	$T_C = 135$ °C, $\delta = 0.5$ square wave	60	Α
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms sinusoidal	500	Α
T _{stg}	Storage temperature range	-65 to +175	°C	
Tj	Operating junction temperature rar	-40 to +175	°C	

Table 3: Thermal parameters

Symbol	Parameter	Max. value	Unit
R _{th(j-c)}	Junction to case	0.45	°C/W

Table 4: Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
I _R ⁽¹⁾ Reverse lea	D	T _j = 25 °C	$V_R = V_{RRM}$	-		5	μА
	Reverse leakage current	T _j = 150 °C		-	25	250	
V _F ⁽²⁾	Forward voltage drop	T _j = 25 °C	I _F = 60 A	-	1.05	1.3	V
		T _j = 150 °C		-	0.95	1.2	

Notes:

 $^{(1)}\text{Pulse}$ test: t_p = 5 ms, δ < 2%

 $^{(2)}$ Pulse test: tp = 380 µs, δ < 2%

To evaluate the conduction losses, use the following equation:

 $P = 0.96 \text{ x } I_{F(AV)} + 0.004 \text{ x } I_{F^{2}(RMS)}$

STBR6012-Y Characteristics

Characteristics (curves)

Figure 1: Average forward power dissipation versus average forward current 100 $\delta = 0.5$ δ = 1 80 δ = 0.2 60 $\delta = 0.05$ 40 20 10 20 30 60 70 80 40 50

Figure 2: Forward voltage drop versus forward current (typical values)

1.0E+03

1.0E+02

1.0E+01

1.0E-01

1.0E-02

0.0

0.5

1.0

1.5

Figure 3: Forward voltage drop versus forward current (maximum values)

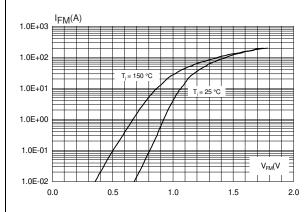


Figure 4: Relative variation of thermal impedance junction to case versus pulse duration

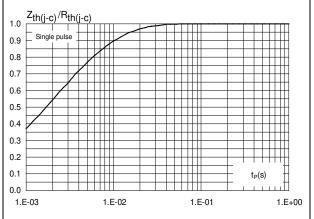
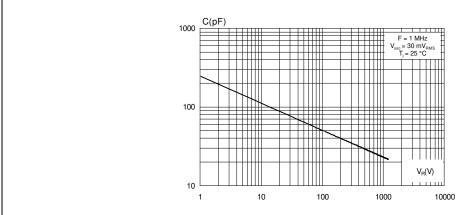


Figure 5: Junction capacitance versus reverse voltage applied (typical values)



Package information STBR6012-Y

2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

• Epoxy meets UL94, V0

Cooling method: by conduction (C)
 Recommended torque value: 0.55 N·m

• Maximum torque value: 1.0 N·m

STBR6012-Y Package information

2.1 DO-247 package information

Figure 6: DO-247 package outline

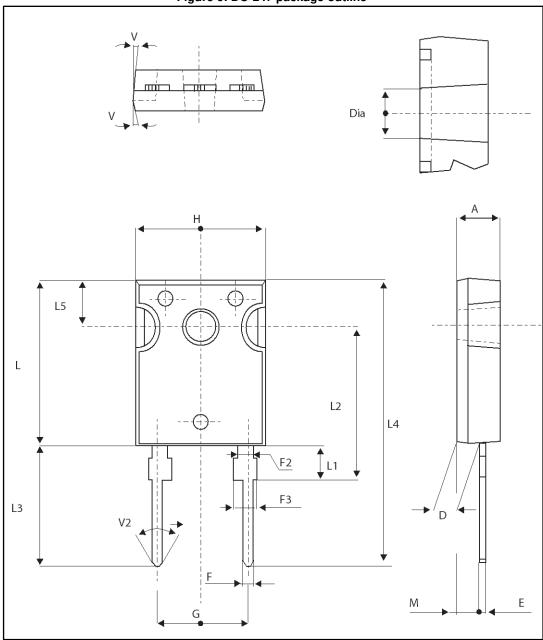


Table 5: DO-247 package mechanical data

	Dimensions				
Ref.	Millim	eters	Inches		
	Min.	Max.	Min.	Max.	
Α	4.85	5.15	0.191	0.203	
D	2.20	2.60	0.086	0.102	
E	0.40	0.80	0.015	0.031	
F	1.00	1.40	0.039	0.055	
F2	2.00 typ.		0.078 typ.		
F3	2.00	2.40	0.078	0.094	
G	10.90 typ.		0.429 typ.		
Н	15.45	15.75	0.608	0.620	
L	19.85	20.15	0.781	0.793	
L1	3.70	4.30	0.145	0.169	
L2	18.50 typ.		0.728 typ.		
L3	14.20	14.80	0.559	0.582	
L4	34.60 typ.		1.362	typ.	
L5	5.50 typ.		0.216	S typ.	
М	2.00	3.00	0.078	0.118	
V	5°		5	0	
V2	60°		60)°	
Dia.	3.55	3.65	0.139	0.143	

STBR6012-Y Ordering information

3 Ordering information

Table 6: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STBR6012WY	STBR6012WY	DO-247	4.4 g	30	Tube

4 Revision history

Table 7: Document revision history

Date	Revision	Changes
07-Nov-2016	1	First issue.

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